

PARA LIGHT ELECTRONICS CO., LTD.

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DATA SHEET

PART NO.: L-S115JRJGCT-U1

REV: <u>A/2</u>

CUSTOMER'S APPROVAL:

DCC:

DRAWING NO. : DS-78-16-005

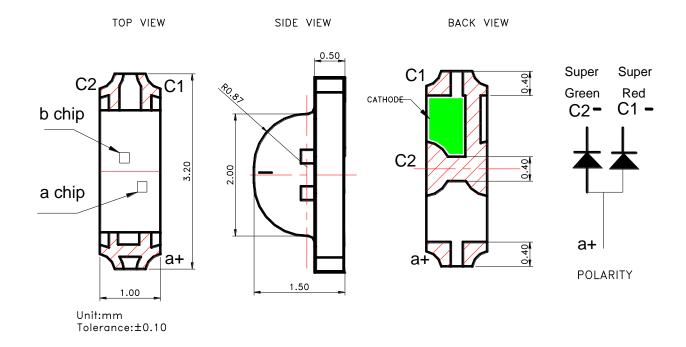
DATE: 2021-11-25

Page 1



Part No.: L-S115JRJGCT-U1 REV: A/2

PACKAGE OUTLINE DIMENSIONS



Notes:

- 1. a chip: Super Red; b chip: Super Green.
- 2. All dimensions are in millimeters.
- 3. Tolerance is \pm 0.1mm (.004") unless otherwise noted.

Features

- * Dual color, <u>common anode</u>, side view Chip LED.
- **★** Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic Pick & Place equipment.
- * Compatible with Reflow soldering and Wave soldering processes.
- * EIA STD package.
- * I.C. compatible.
- * Pb free product.
- * Meet RoHS Green Product.
- * Moisture sensitivity level: 3



REV: A / 2

Part No.: L-S115JRJGCT-5A

Chip Materials

chip	Light Color	Dice Material	Lens Color
a	JR: Super Red	A Har Co D	Water Class
b	JG: Super Green	AlInGaP	Water Clear

• Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rat	Unit	
Symbol	i arameter	Super Red	Super Green	Oilit
PD	Power Dissipation	75	60	mW
Inc	Peak Forward Current	80	60	mA
IPF	(1/10 Duty Cycle, 0.1ms Pulse Width)	00	60	
IF	Continuous Forward Current	30	30	mA
V_R	Reverse Voltage	5	5	V
ESD	Electrostatic Discharge Threshold(HBM) ^{Note A}	20	V	
Topr	Operating Temperature Range -40 ~ +85		°C	
Tstg	Storage Temperature Range -40 ~ +85			°C

Note A:

HBM: Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD

• Electro-Optical Characteristics(Ta=25°C)

	Symbol	Super Red	Super Green	Unit	Test Condition
Min.	IV	7.1	4.5		IF=5mA
Typ.		15	8	mcd	
Max.		28	18]	
Typ.	2θ1/2	130		deg	Note 2
Min		625	567		
Typ.	λd	630	570	nm	IF=5mA
Max		635	576		
Typ.	Δλ	17	15	nm	
Min.		1.7	1.8		
Typ.	VF	1.8	1.95	V	IF = 5mA
Max.		2.1	2.2		
Max.	IR	10		μA	VR = 5V
	Typ. Max. Typ. Min Typ. Max Typ. Min. Typ. Min. Typ. Min. Typ. Min.	Min. Typ. IV Max. IV Typ. 2θ1/2 Min Typ. λd Max Typ. Δλ Min. Typ. VF Max. VF	Min. 7.1 Typ. IV Max. 28 Typ. 201/2 Min 625 Typ. λd Max 630 Max 635 Typ. Δλ Min. 1.7 Typ. VF Max. 2.1	Min. 7.1 4.5 Typ. IV 15 8 Max. 28 18 Typ. 291/2 130 Min 625 567 Typ. λd 630 570 Max 635 576 Typ. Δλ 17 15 Min. 1.7 1.8 Typ. VF 1.8 1.95 Max. 2.1 2.2	Min. 7.1 4.5 Typ. IV 15 8 mcd Max. 28 18 mcd Typ. 291/2 130 deg Min 625 567 mm Typ. λd 630 570 nm Max 635 576 mm Typ. Δλ 17 15 nm Min. 1.7 1.8 mm Typ. VF 1.8 1.95 V Max. 2.1 2.2 2.2



Part No.: L-S115JRJGCT-5A REV: A / 2

Bin Code List

Luminous Intensity(IV), Unit:mcd@5mA					
Super Red(a chip)			Super Green(b chip)		
Bin Code	Min	Max	Bin Code	Min	Max
K	7.1	11.2	J	4.5	7.1
L	11.2	18	K	7.1	11.2
M	18	28	L	11.2	18

Tolerance of each bin are $\pm 15\%$

Forward Voltage(VF), Unit:V@5mA					
Super Red(a chip)			Super Green(b chip)		
Bin Code	Min	Max	Bin Code	Min	Max
2	1.7	1.8	3	1.8	1.9
3	1.8	1.9	4	1.9	2.0
4	1.9	2.0	5	2.0	2.1
5	2.0	2.1	6	2.1	2.2

Tolerance of each bin are ± 0.1 Volt

Dominant Wavelength (Hue),Unit: nm@5mA				
Yellow Green(b chip)				
Bin Code	Min Max			
GA	567	570		
GB	570	573		
GC	573	576		

Tolerance of each bin are ± 1 nm

Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength λd is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD:

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

5. Major standard testing equipment by "Instrument System" Model: CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model: 2400.



Part No.: L-S115JRJGCT-U1

REV: A / 2

Super Red Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

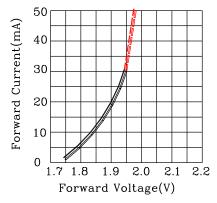


Fig.2 Forward Current vs.Forward Voltage

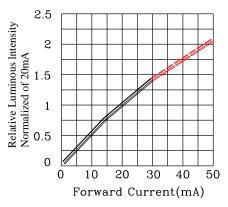


Fig.4 Relative Luminous Intensity vs.Forward Current

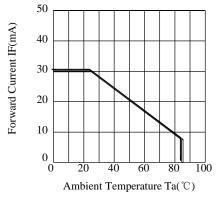


Fig.6 Forward Current Derating Curve

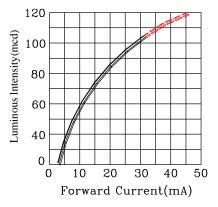


Fig.3 Luminous Intensity vs.Forward Current

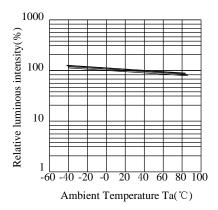


Fig.5 Luminous Intensity vs.Ambient Temperature

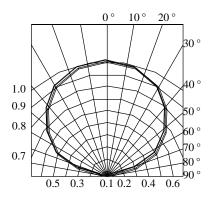


Fig.7 Relative Intensity vs.Angle



50

Part No.: L-S115JRJGCT-U1

REV: A / 2

Super Green Typical Electro-Optical Characteristics Curves

(25°CAmbient Temperature Unless Otherwise Noted)

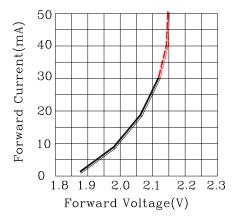
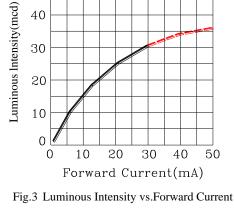


Fig.2 Forward Current vs.Forward Voltage



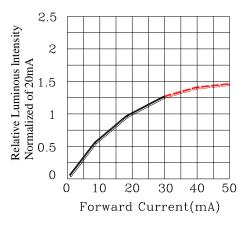


Fig.4 Relative Luminous Intensity vs.Forward Current

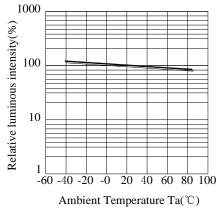


Fig.5 Luminous Intensity vs. Ambient Temperature

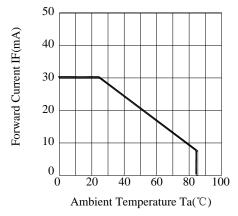


Fig.6 Forward Current Derating Curve

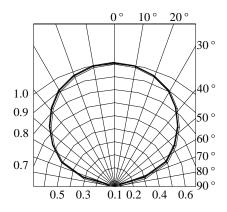


Fig.7 Relative Intensity vs.Angle



Part No.: L-S115JRJGCT-5A

REV: A / 2

Label Explanation



ITEM CODE:PARRA LIGHT

PART NO: L-S115JRJGCT-5A

IV --- Luminous Intensity Code

LOT NO: EM S L 12 09 0110
A B C D E F

A---EM: Emos Code

B---S:SMD

L---Local

D---Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG:

3000pcs for 150, 170, 110, 155, 115 series

4000pcs for 191 series

5000pcs for 192 series

DATE CODE: 2012 09 10

G H I

G--- Year

H--- Month

I --- Day



Part No.: L-S115JRJGCT-U1

REV: A/2

Typical Electro-Optical Characteristics Curves

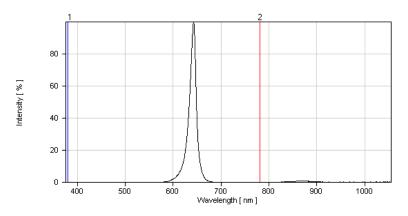
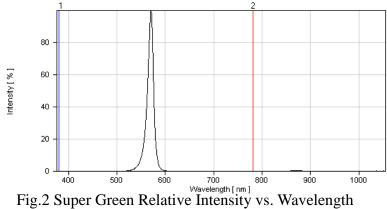
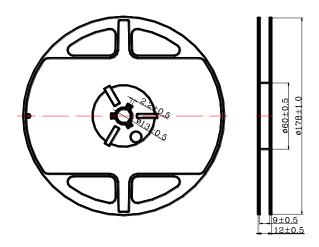


Fig.1 Super Red Relative Intensity vs. Wavelength



Reel Dimensions



Notes:

- Taping Quantity: 3000pcs.
- The tolerances unless mentioned is ± 0.1 mm, Angle $\pm 0.5^{\circ}$, Unit: mm.

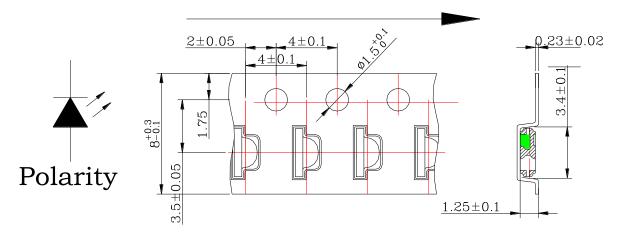


Part No.: L-S115JRJGCT-U1

REV: A / 2

Package Dimensions Of Tape And Reel

Progressive direction



Notes: All dimensions are in millimeters.



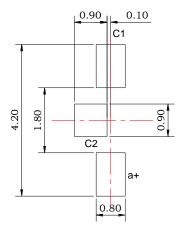
Part No.: L-S115JRJGCT-U1

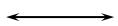
REV: A / 2

Cleaning

- * If cleaning is required, use the following solutions for less than 1 minute and less than 40°C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- * Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Suggest Soldering Pad Dimensions





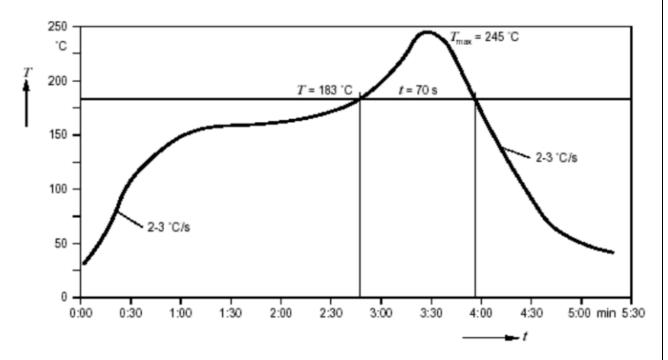
Direction of PWB camber and go to reflow furnace



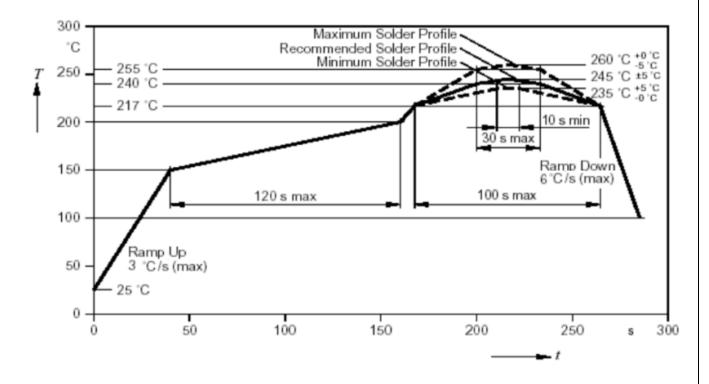
Part No.: L-S115JRJGCT-5A

REV: A / 2

• Suggest Sn/Pb IR Reflow Soldering Profile Condition:



• Suggest Pb-Free IR Reflow Soldering Profile Condition:





Part No.: L-S115JRJGCT-5A REV: A / 2

CAUTIONS

1. Application Limitation:

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage:

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: $60\pm5^{\circ}$ C for 24 hours.

3.Soldering(Standard Process):

Do not apply any stress to the lead frame during soldering while the LED is at high temperature. Recommended soldering condition.

Reflow Soldering:

Pre-heat 120~150 ℃, 120sec. MAX., Peak temperature : 240 ℃ Max. Soldering time : 10 sec Max.

Soldering Iron: (Not recommended)

Pre-heat 100 ℃ Max, Pre-heat time 60s Max, Solder wave 260 ℃ Max, Soldering time 5 sec. Max. preformed consecutively cooling process is required between 1st and 2nd soldering processes.



Part No.: L-S115JRJGCT-U1 REV: A/2

4. Lead-Free Soldering

For Reflow Soldering:

1、 Pre-Heat Temp: 150-180°C,120sec.Max.

2. Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.

3、Peak Temperature : 260°C, 5sec.

4. Reflow Repetition: 2 Times Max.

5. Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

For Soldering Iron (Not Recommended):

1、Iron Tip Temp: 350°C Max.

2. Soldering Iron: 30w Max.

3. Soldering Time: 3 Sec. Max. One Time.

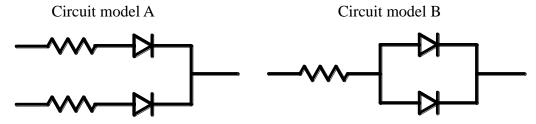
For Dip Soldering:

1、Pre-Heat Temp: 150°C Max. 120 Sec. Max.

2、Bath Temp: 265°C Max.

3. Dip Time: 5 Sec. Max.

5. Drive Method



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.